

NOTES:

1. MATERIAL:

1.1 HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP;
UL94V-0.

1.2 CONTACT: COPPER ALLOY.

1.3 FITTING NAIL: COPPER ALLOY

2. FINISH:

2.1 TERMINAL CONTACT:

50u" MIN. NICKEL UNDERPLATING OVERALL.

1: GOLD FLASH ON CONTACT AND SOLDER AREA

N: 50u" MIN MATT TIN ON CONTACT AND SOLDER AREA

C: 15u" GOLD PLATING ON CONTACT AND GOLD FLASH ON SOLDER AREA

T: 10u" GOLD PLATING ON CONTACT AND GOLD FLASH ON SOLDER AREA

2.2 FITTING NAIL:

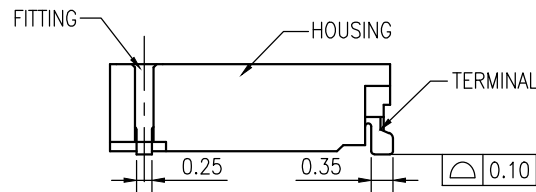
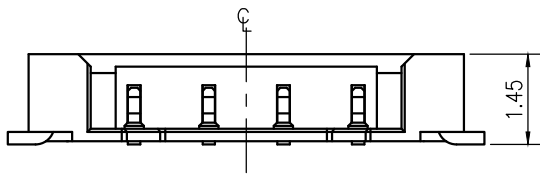
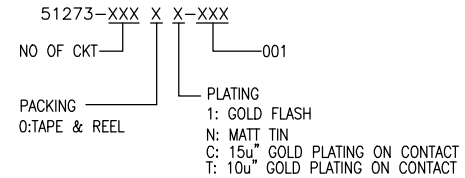
50u" MIN. NICKEL UNDERPLATING OVERALL.

100u" MIN. MATT TIN PLATING

3. SPEC. PLS. REFER TO PS-50269-XXXX-XXX

4. PACKAGE PLS. REFER TO 51220-XXXX-05-TRP

5. PART NUMBER



CKT	Dim A	Dim B	Dim C	Dim D
2	1.2	2.6	3.3	4.6
3	2.4	3.8	4.5	5.8
4	3.6	5.0	5.7	7.0
5	4.8	6.2	6.9	8.2
6	6.0	7.4	8.1	9.4
8	8.4	9.8	10.5	11.8
10	10.8	12.2	12.9	14.2

QUALITY SYMBOLS MAJOR CRITICAL	DRAWN BY YanJinXiu	DATE 21/07/16	
	CHECKED BY BRAVE	DATE 21/07/16	
GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	APPROVED BY BRAVE	DATE 21/07/16	TITLE 1.2mm PITCH WTB WAFER CONNECTOR
	UNITS mm		SIZE A4
SCALE 1:1	SHEET NO. 1 OF 1	REV H	DWG NO. 51273-XXXXX-XXX

单击下面可查看定价，库存，交付和生命周期等信息

[>>ACES\(宏致\)](#)